

Please note that Cypress is an Infineon Technologies Company.

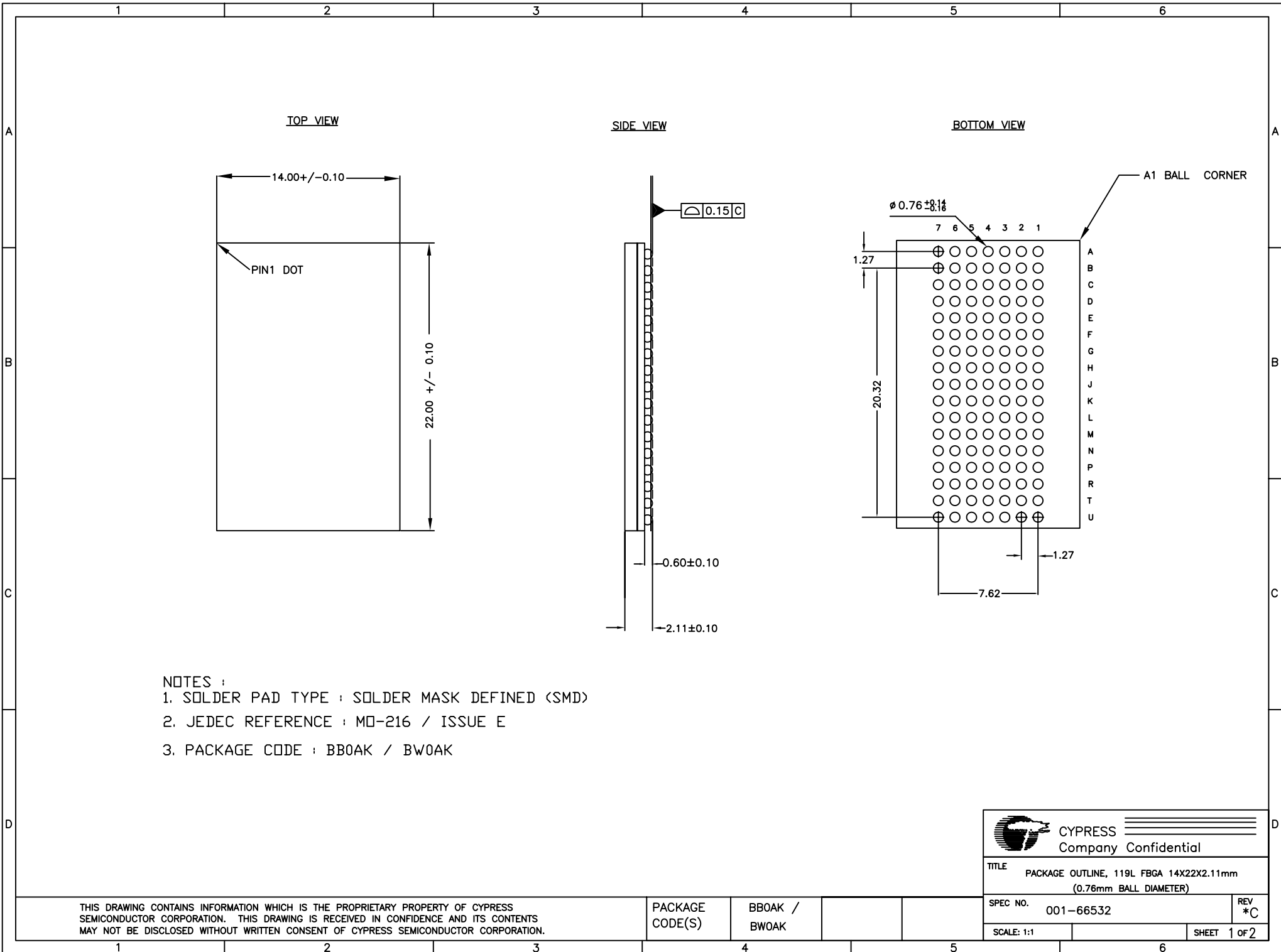
The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.



REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	—	■A	3136554	NEW RELEASE	01/10/11	
1	—	■B	3174484	ADDED QMD UNIT ON SPEC TITLE TO MATCH WITH DMS	02/15/11	
1	—	■B	3567854	CHANGED TITLE TO REFLECT PACKAGE HEIGHT AND ADDED PACKAGE WEIGHT REFERENCE TO PMDD	03/30/12	
1	—	■C	4264485	SUNSET REVIEW FOLLOW CYPRESS STANDARD PACKAGE OUTLINE TEMPLATE	01/27/14	



TITLE	PACKAGE OUTLINE, 119L FBGA 14X22X2.11mm (0.76mm BALL DIAMETER)
-------	---

SCALE: 1:1		SHEET 2 OF 2
------------	--	--------------

THIS DRAWING CONTAINS INFORMATION WHICH IS THE PROPRIETARY PROPERTY OF CYPRESS SEMICONDUCTOR CORPORATION. THIS DRAWING IS RECEIVED IN CONFIDENCE AND ITS CONTENTS MAY NOT BE DISCLOSED WITHOUT WRITTEN CONSENT OF CYPRESS SEMICONDUCTOR CORPORATION.

BBOAK /
BWOAK

REV
*C